



P-Channel 20 V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}\left(\Omega\right)$	I _D (A) ^a	Q _g (Typ.)			
	0.060 at V _{GS} = - 4.5 V	- 4.7				
- 20	0.084 at V _{GS} = - 2.7 V	- 3.9	7.53 nC			
	0.100 at V _{GS} = - 2.5 V	- 3.4				

FEATURES

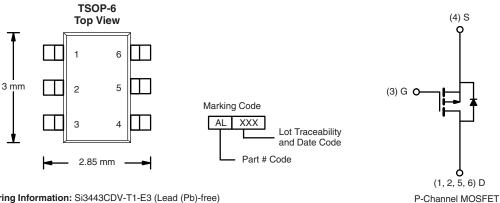
- Halogen-free According to IEC 61249-2-21 Definition
- TrenchFET® Power MOSFET
- **PWM Optimized**
- 100 % R_g Tested
- Compliant to RoHS Directive 2002/95/EC



HALOGEN FREE

APPLICATIONS

- HDD
- Asynchronous Rectification
- Load Switch for Portable Devices



Ordering Information: Si3443CDV-T1-E3 (Lead (Pb)-free)

Si3443CDV-T1-GE3 (Lead (Pb)-free and Halogen-free)

Limit	Unit
- 20	V
± 12	•
- 5.97	
- 4.6	
- 4.7 ^{b, c} - 3.4 ^{b, c}	
- 3.4 ^{b, c}	Α
- 20	
- 2.67	
- 1.71 ^{b, c}	
3.2	

Parameter	Symbol	Limit	Unit		
Drain-Source Voltage		V _{DS}	- 20	V	
Gate-Source Voltage		V_{GS}	± 12	•	
	T _C = 25 °C		- 5.97		
Continuous Drain Current (T _{.1} = 150 °C)	T _C = 70 °C		- 4.6		
Continuous Brain Current (1) = 100 O)	T _A = 25 °C	lo	- 4.7 ^{b, c}		
	T _A = 70 °C	1	- 3.4 ^{b, c}	A	
Pulsed Drain Current		I _{DM}	- 20		
Continuous Source-Drain Diode Current	T _C = 25 °C		- 2.67		
Continuous Source-Diain Diode Current	T _A = 25 °C	Is	- 1.71 ^{b, c}		
	T _C = 25 °C		3.2		
Manipular Danier Disabation	T _C = 70 °C	1 , —	2.05		
Maximum Power Dissipation	T _A = 25 °C	P _D	2 ^{b, c}	W	
	T _A = 70 °C	1	1.28 ^{b, c}		
Operating Junction and Storage Temperature	T _J , T _{stg}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS							
Parameter	Symbol	Typical	Maximum	Unit			
Maximum Junction-to-Ambient ^{b, d}	t ≤ 5 s	R_{thJA}	51	62.5	°C/W		
Maximum Junction-to-Foot (Drain)	Steady State	R_{thJF}	32	39	0, ••		

Notes:

- a. Based on $T_C = 25$ °C.
- b. Surface mounted on 1" x 1" FR4 board.
- c. t = 5 s.
- d. Maximum under steady state conditions is 110 °C/W.

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Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = -250 \mu\text{A}$	- 20			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = - 250 μA		- 18.8		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_J$	ID=-250 μΑ		3.25		mv/°C	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = -250 \mu A$	- 0.6		- 1.5	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 12 \text{ V}$			± 100	nA	
7 0		V _{DS} = - 20 V, V _{GS} = 0 V			- 1	μΑ	
Zero Gate Voltage Drain Current	I _{DSS}	$V_{DS} = -20 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$			- 10		
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge -5 \text{ V}, V_{GS} = -4.5 \text{ V}$	- 20			Α	
		V _{GS} = - 4.5 V, I _D = - 4.7 A		0.0500	0.0600	Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	V _{GS} = - 2.7 V, I _D = - 3.9 A		0.0692	0.0840		
		V _{GS} = - 2.5 V, I _D = - 3.4 A		0.0830	0.1000		
Forward Transconductance ^a	9 _{fs}	V _{DS} = - 10 V, I _D = - 4.7 A		15		S	
Dynamic ^b							
Input Capacitance	C _{iss}			610		pF	
Output Capacitance	C _{oss}	$V_{DS} = -10 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		132			
Reverse Transfer Capacitance	C _{rss}			105			
Total Cata Charge		$V_{DS} = -10 \text{ V}, V_{GS} = -5 \text{ V}, I_{D} = -4.7 \text{ A}$		8.26	12.4	nC	
Total Gate Charge	Q_g			7.53	11.3		
Gate-Source Charge	Q_{gs}	$V_{DS} = -10 \text{ V}, V_{GS} = -4.5 \text{ V}, I_{D} = -4.7 \text{ A}$		1.53			
Gate-Drain Charge	Q_{gd}			2.37			
Gate Resistance	R_{g}	f = 1 MHz	1.7	8.5	12.75	Ω	
Turn-On Delay Time	t _{d(on)}			27	41		
Rise Time	t _r	$V_{DD} = -10 \text{ V}, R_L = 2.12 \Omega$		59	88.5	ns	
Turn-Off Delay Time	t _{d(off)}	$I_D \cong$ - 4.7 A, V_{GEN} = - 4.5 V, R_g = 1 Ω		30	45		
Fall Time	t _f			11	16.5		
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	I _S	T _C = 25 °C			- 2.67	Α	
Pulse Diode Forward Current ^a	I _{SM}				- 20	^	
Body Diode Voltage	V_{SD}	I _S = - 1.7 A		- 0.8	- 1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			20	30	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	L = 1.7.4 dl/dt = 100.4/10. T = 05.90		9	13.5	nC	
Reverse Recovery Fall Time	t _a	$I_F = -1.7 \text{ A}, \text{ dI/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$		15			
Reverse Recovery Rise Time	t _b			5.1		ns	

Notes:

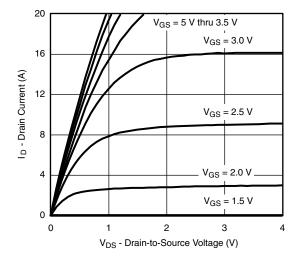
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$

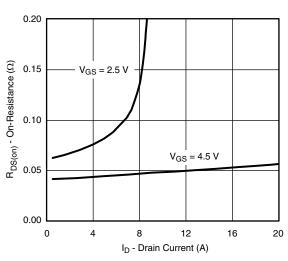
b. Guaranteed by design, not subject to production testing.



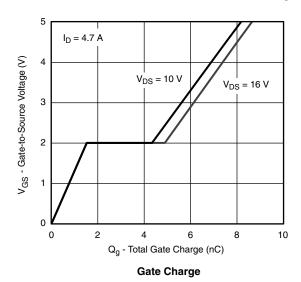
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

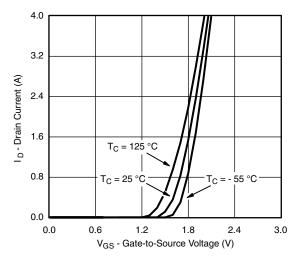


Output Characteristics

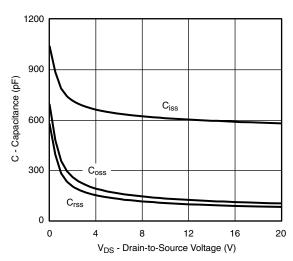


On-Resistance vs. Drain Current and Gate Voltage

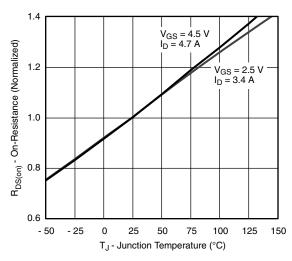




Transfer Characteristics



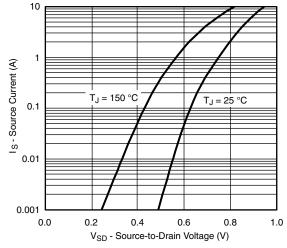
Capacitance

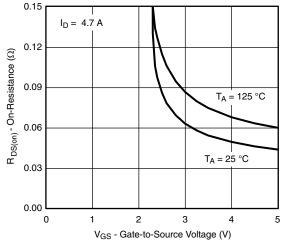


On-Resistance vs. Junction Temperature

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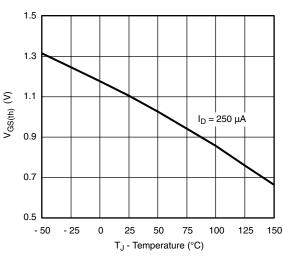
TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)

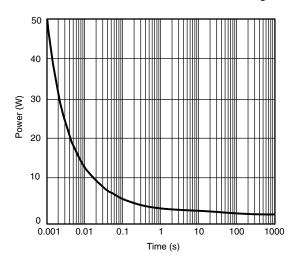




Source-Drain Diode Forward Voltage

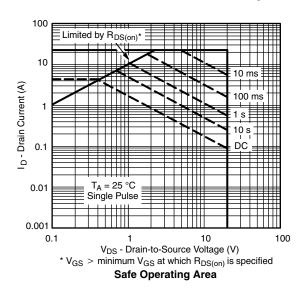
On-Resistance vs. Gate-to-Source Voltage





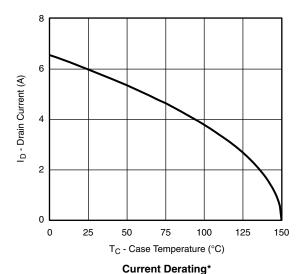
Threshold Voltage

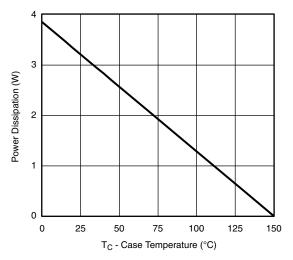
Single Pulse Power, Junction-to-Ambient





TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



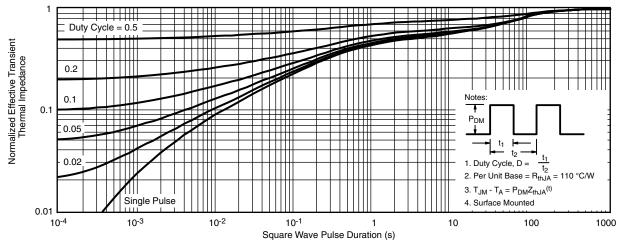


Power, Junction-to-Foot

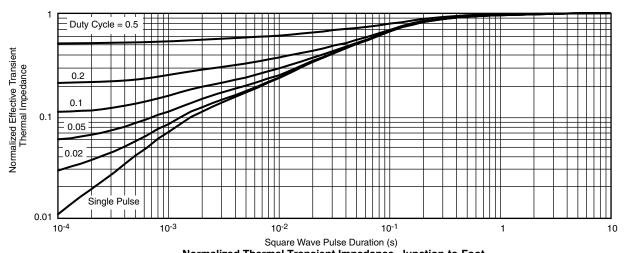
^{*} The power dissipation P_D is based on $T_{J(max.)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

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TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

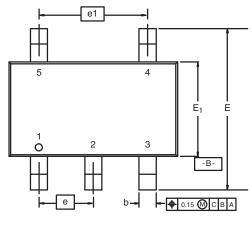
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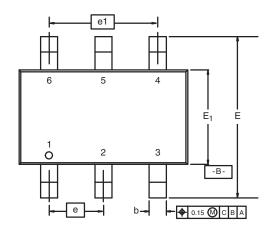




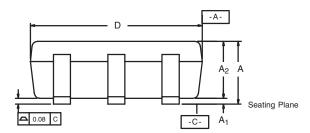
TSOP: 5/6-LEAD

JEDEC Part Number: MO-193C

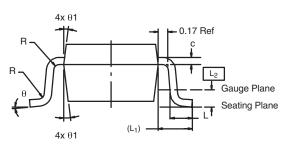




5-LEAD TSOP







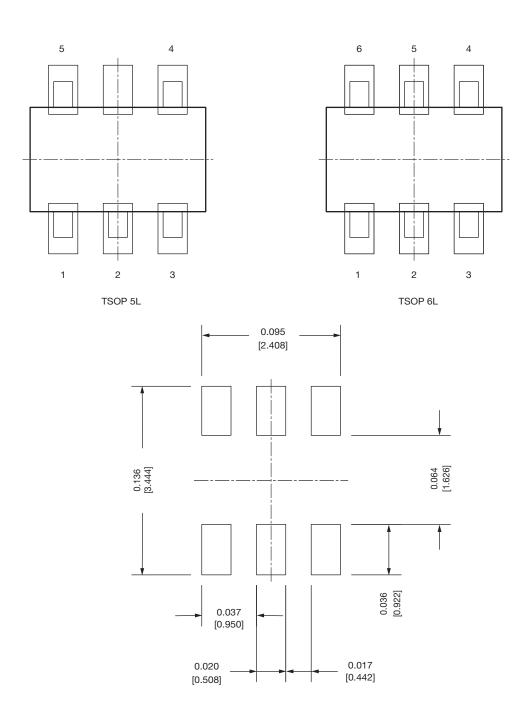
	MIL	LIMETER	RS	INCHES			
Dim	Min	Nom	Max	Min	Nom	Max	
Α	0.91	-	1.10	0.036	-	0.043	
A ₁	0.01	-	0.10	0.0004	-	0.004	
A ₂	0.90	-	1.00	0.035	0.038	0.039	
b	0.30	0.32	0.45	0.012	0.013	0.018	
С	0.10	0.15	0.20	0.004 0.006 0.0			
D	2.95	3.05	3.10	0.116 0.120 0.			
E	2.70	2.85	2.98	0.106	0.112	0.117	
E ₁	1.55	1.65	1.70	0.061	0.065	0.067	
е		0.95 BSC		0.0374 BSC			
e ₁	1.80	1.90	2.00	0.071	0.075	0.079	
L	0.32	-	0.50	0.012	-	0.020	
L ₁	0.60 Ref			0.024 Ref			
L ₂	0.25 BSC			0.010 BSC			
R	0.10	-	-	0.004	-	-	
θ	0°	4°	8°	0°	4°	8°	
θ1		7° Nom			7° Nom		
ECN: C-06593-Rev. I, 18-Dec-06 DWG: 5540							

DWG: 5540

Document Number: 71200 18-Dec-06



Recommended Land Pattern For TSOP-5L / TSOP-6L



Note

• All dimensions are in inches (millimeter)

ECN: C22-0860-Rev. B, 24-Oct-2022 DWG: 3010



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